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FDS6630A

N-Channel Logic Level PowerTrench™ MOSFET

General Description

This N-Channel Logic Level MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize on-state resistance and yet maintain superior switching performance.

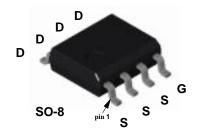
These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

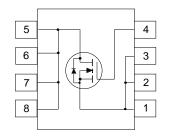
Applications

- DC/DC converter
- Load switch
- Motor drives

Features

- 6.5 A, 30 V. $R_{DS(on)} = 0.038 \ \Omega \ @ V_{GS} = 10 \ V$ $R_{DS(on)} = 0.053 \ \Omega \ @ V_{GS} = 4.5 \ V$
- Low gate charge (5nC typical).
- Fast switching speed.
- \bullet High performance trench technology for extremely low $R_{\mbox{\tiny DS(ON)}}.$
- High power and current handling capability.





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		30	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Drain Current - Continuous	(Note 1a)	6.5	А
	- Pulsed		40	
P _D	Power Dissipation for Single Operation	(Note 1a)	2.5	W
		(Note 1b)	1.2	
		(Note 1c)	1	
T _J , T _{stg}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

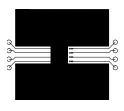
$R_{ heta^{JA}}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	°C/W
$R_{\theta^{JC}}$	Thermal Resistance, Junction-to-Case	(Note 1)	25	°C/W

Package Outlines and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
FDS6630A	FDS6630A	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	30			V
ABVDSS ΔTJ	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C		24		mV/∘C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1	1.7	3	V
<u>A</u> VGS(th) ΛΤ _J	Gate Threshold Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C		-4		mV/∘C
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 6.5 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 6.5 \text{ A}, T_J = 125 ^{\circ}\text{C}$ $V_{GS} = 4.5 \text{ V}, I_D = 5.5 \text{ A}$		0.028 0.044 0.040	0.038 0.060 0.053	Ω
I _{D(on)}	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 5 V	20			Α
g FS	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 6.5 \text{ A}$		13		S
Dvnamio	Characteristics					
Ciss	Input Capacitance	V _{DS} = 15 V, V _{GS} = 0 V,		460		pF
Coss	Output Capacitance	f = 1.0 MHz		115		pF
C _{rss}	Reverse Transfer Capacitance			45		pF
Switchin	g Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 15 \text{ V}, I_{D} = 1 \text{ A},$		5	11	ns
t _r	Turn-On Rise Time	V_{GS} = 10 V, R_{GEN} = 6 Ω		8	17	ns
t _{d(off)}	Turn-Off Delay Time			17	28	ns
t _f	Turn-Off Fall Time			13	24	ns
Q _q	Total Gate Charge	$V_{DS} = 5 \text{ V}, I_{D} = 6.5 \text{ A},$		5	7	nC
$\overline{Q_{gs}}$	Gate-Source Charge	$V_{GS} = 5 \text{ V}$		2		nC
Q_{gd}	Gate-Drain Charge			0.9		nC
Drain-Sc	ource Diode Characteristics and	d Maximum Ratings				
ls	Maximum Continuous Drain-Source Did				2.1	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 2.1 A (Note 2)		0.8	1.2	V

^{1:} R_{BJA} is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 50° C/W when mounted on a 1 in² pad of 2 oz. copper.



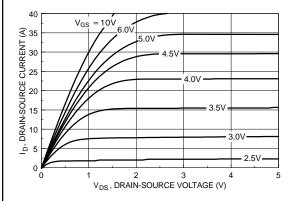
b) 105° C/W when mounted on a 0.04 in² pad of 2 oz. copper.



Scale 1 : 1 on letter size paper

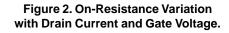
2: Pulse Test: Pulse Width $\leq 300~\mu\text{s},~\text{Duty Cycle} \leq 2.0\%$

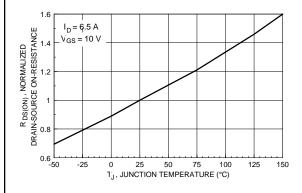
Typical Characteristics



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Figure 1. On-Region Characteristics.





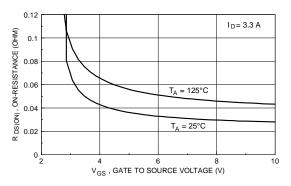
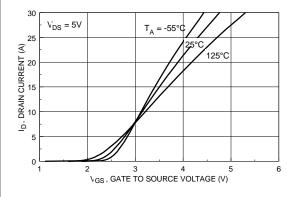


Figure 3. On-Resistance Variation with Temperature.

Figure 4. On-Resistance Variation with Gate-to-Source Voltage.



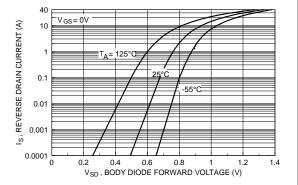
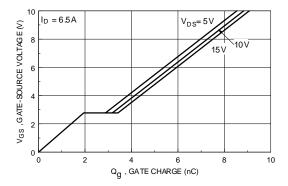


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)



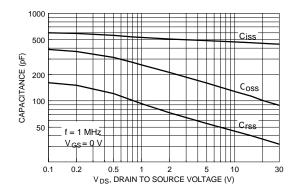
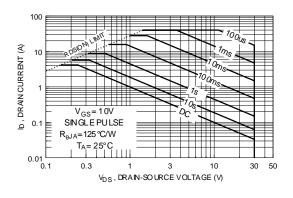


Figure 7. Gate-Charge Characteristics.





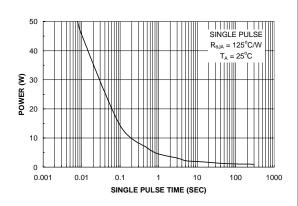


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

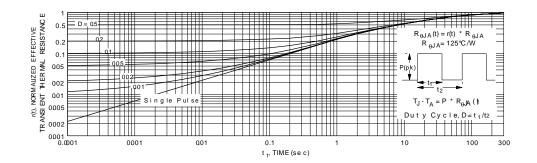


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient themal response will change depending on the circuit board design.

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